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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20640**

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**Issue Date:** 15-Sep-2014

**TITLE:** NCP6343 Wafer Probe ATE Qualification at UTAC and CSP Bump Qualification at FCI.

**PROPOSED FIRST SHIP DATE:** 3-Jan-2015

**AFFECTED CHANGE CATEGORY(S):** Assembly Site

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or Todd Manes <[todd.manes@onsemi.com](mailto:todd.manes@onsemi.com)>

**SAMPLES:**

Contact your local ON Semiconductor Sales Office or Mat Hilton <[mat.hilton@onsemi.com](mailto:mat.hilton@onsemi.com)>

**ADDITIONAL RELIABILITY DATA:**

Contact your local ON Semiconductor Sales Office or Ken Fergus <[ken.fergus@onsemi.com](mailto:ken.fergus@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

This PCN is to notify ON Semiconductor's customer's that the NCP6343 family of devices are now qualified at UTAC (Singapore) for ATE wafer probing and CSP bumping at FCI (Phoenix, AZ, USA).

The affected devices listed on this PCN are currently bumped at Deca (Philippines) and ATE wafer probed at ON Semiconductor Seremban, Malaysia facility (SBN). Upon expiration of this FPCN, or early customer approval, these devices may be processed at either Deca or FCI for CSP wafer bumping and SBN or UTAC for ATE wafer probing.

The package outline and electrical performance of the NCP6343 family from UTAC and FCI fully meet datasheet specifications.

**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20640****RELIABILITY DATA SUMMARY:**

The FCI bump on pad process has been previously qualified and is currently being used on many devices. In addition, the NCP6343 had the following reliability tests performed.

Electrostatic Discharge	Human Body Model (HBM)	Pass 2000V
Electrostatic Discharge	Machine Model (MM)	Pass 150V
Electrostatic Discharge	Charge Device Model (CDM)	Pass 2000V
Latch Up	Digital Pins	Pass $\pm 10\text{mA}$
	All Other Pins	Pass $\pm 100\text{mA}$
Electrical Distribution	Critical Parameters (untrimmed)	Cpk $\geq 1.67$

**ELECTRICAL CHARACTERISTIC SUMMARY:**

Electrical characteristic meet device specifications.

**CHANGED PART IDENTIFICATION:**

Upon expiration of this FPCN, or early customer approval, Deca and FCI will follow the ON Semiconductor standard marking for CSP packages. The CSP bump location can be identified by the assembly code seen on the top marking.

Deca assembly code: d

FCI assembly code: F

**LIST OF AFFECTED GENERAL PART NUMBERS:**

NCP6343FCT1G  
NCP6343BFCCT1G  
NCP6343DFCCT1G